

STARPOWER

SEMICONDUCTOR

IGBT

GD1500SGL330A4S

3300V/1500A 1 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as high power converters.

Features

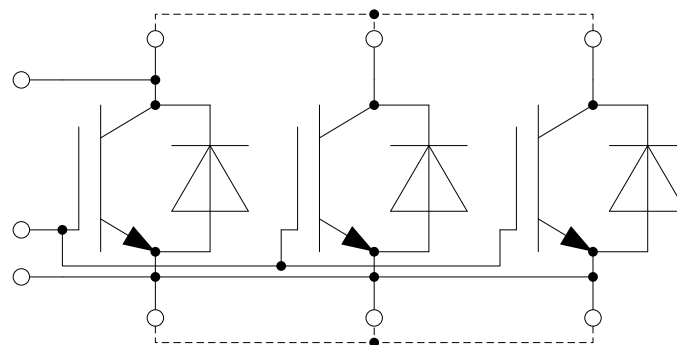
- Low $V_{CE(sat)}$ SPT+ IGBT technology
- Low switching losses
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- AlSiC baseplate for high power cycling capability
- AlN substrate for low thermal resistance
- High reliability package



Typical Applications

- High Power Converter
- Wind Power
- Traction Drive

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	3300	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	3000 1500	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	3000	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	17.65	kW

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	3300	V
I_F	Diode Continuous Forward Current	1500	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	3000	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	6000	V
V_{ISO}	Partial Discharge Extinction Voltage IEC1287, RMS, $f=50\text{Hz}$, $Q_{PD}\leq 10\text{pC}$	2600	V

IGBT Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=1500\text{A}, V_{GE}=15\text{V}, T_j=25^\circ\text{C}$		2.50	2.90	V	
		$I_C=1500\text{A}, V_{GE}=15\text{V}, T_j=125^\circ\text{C}$		3.10			
		$I_C=1500\text{A}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}$		3.25			
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=240\text{mA}, V_{CE}=V_{GE}, T_j=25^\circ\text{C}$	5.0		7.0	V	
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$			5.0	mA	
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$			500	nA	
R_{Gint}	Internal Gate Resistance			0.6		Ω	
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		151		nF	
C_{res}	Reverse Transfer Capacitance				3.85		nF
Q_G	Gate Charge	$V_{CE}=1800\text{V}, V_{GE}=-15\dots+15\text{V}$		11.0		μC	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=1800\text{V}, I_C=1500\text{A}, R_{Gon}=1.0\Omega, R_{Goff}=1.5\Omega, C_{GE}=330\text{nF}, V_{GE}=\pm 15\text{V}, T_j=25^\circ\text{C}$		600		ns	
t_r	Rise Time			240		ns	
$t_{d(off)}$	Turn-Off Delay Time			1600		ns	
t_f	Fall Time			390		ns	
E_{on}	Turn-On Switching Loss			1600		mJ	
E_{off}	Turn-Off Switching Loss			2100		mJ	
$t_{d(on)}$	Turn-On Delay Time		$V_{CC}=1800\text{V}, I_C=1500\text{A}, R_{Gon}=1.0\Omega, R_{Goff}=1.5\Omega, C_{GE}=330\text{nF}, V_{GE}=\pm 15\text{V}, T_j=125^\circ\text{C}$		610		ns
t_r	Rise Time				270		ns
$t_{d(off)}$	Turn-Off Delay Time				1760		ns
t_f	Fall Time				445		ns
E_{on}	Turn-On Switching Loss			2150		mJ	
E_{off}	Turn-Off Switching Loss			2800		mJ	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=1800\text{V}, I_C=1500\text{A}, R_{Gon}=1.0\Omega, R_{Goff}=1.5\Omega, C_{GE}=330\text{nF}, V_{GE}=\pm 15\text{V}, T_j=150^\circ\text{C}$			610		ns
t_r	Rise Time				280		ns
$t_{d(off)}$	Turn-Off Delay Time				1800		ns
t_f	Fall Time				470		ns
E_{on}	Turn-On Switching Loss			2350		mJ	
E_{off}	Turn-Off Switching Loss			3000		mJ	
I_{SC}	SC Data		$t_p \leq 10\mu\text{s}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}, V_{CC}=2500\text{V}, V_{CEM} \leq 3300\text{V}$		6400		A

Diode Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
V_F	Diode Forward Voltage	$I_F=1500\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$		2.05	2.50	V	
		$I_F=1500\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$		2.25			
		$I_F=1500\text{A}, V_{GE}=0\text{V}, T_j=150^\circ\text{C}$		2.20			
Q_r	Recovered Charge	$V_R=1800\text{V}, I_F=1500\text{A},$ $-di/dt=6000\text{A}/\mu\text{s}, C_{GE}=330\text{nF},$ $V_{GE}=-15\text{V}, T_j=25^\circ\text{C}$		950		μC	
I_{RM}	Peak Reverse Recovery Current			1700		A	
E_{rec}	Reverse Recovery Energy			1150		mJ	
Q_r	Recovered Charge			1550		μC	
I_{RM}	Peak Reverse Recovery Current		$V_R=1800\text{V}, I_F=1500\text{A},$ $-di/dt=6000\text{A}/\mu\text{s}, C_{GE}=330\text{nF},$ $V_{GE}=-15\text{V}, T_j=125^\circ\text{C}$		1850		A
E_{rec}	Reverse Recovery Energy			1900		mJ	
Q_r	Recovered Charge			1800		μC	
I_{RM}	Peak Reverse Recovery Current		$V_R=1800\text{V}, I_F=1500\text{A},$ $-di/dt=6000\text{A}/\mu\text{s}, C_{GE}=330\text{nF},$ $V_{GE}=-15\text{V}, T_j=150^\circ\text{C}$		1900		A
E_{rec}	Reverse Recovery Energy			2250		mJ	

Module Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		6		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		0.12		m Ω
$R_{\theta JC}$	Junction-to-Case (per IGBT)			8.50	K/kW
	Junction-to-Case (per Diode)			17.0	
$R_{\theta CS}$	Case-to-Sink (per IGBT)		9.00		K/kW
	Case-to-Sink (per Diode)		18.0		
$R_{\theta CS}$	Case-to-Sink		6.0		K/kW
M	Terminal Connection Torque, Screw M4	1.8		2.1	N.m
	Terminal Connection Torque, Screw M8	8.0		10	
	Mounting Torque, Screw M6	4.25		5.75	
G	Weight of Module		1200		g

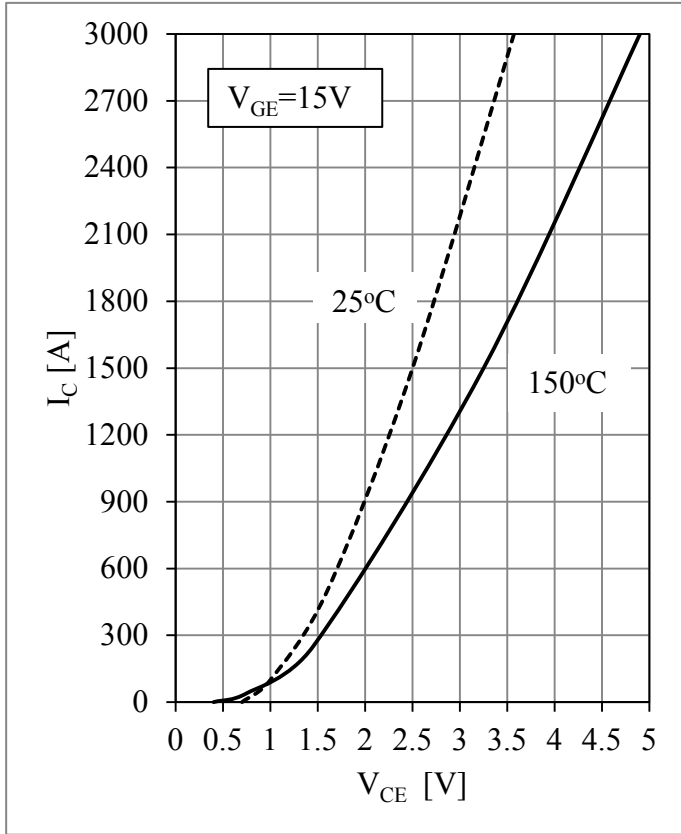


Fig 1. IGBT Output Characteristics

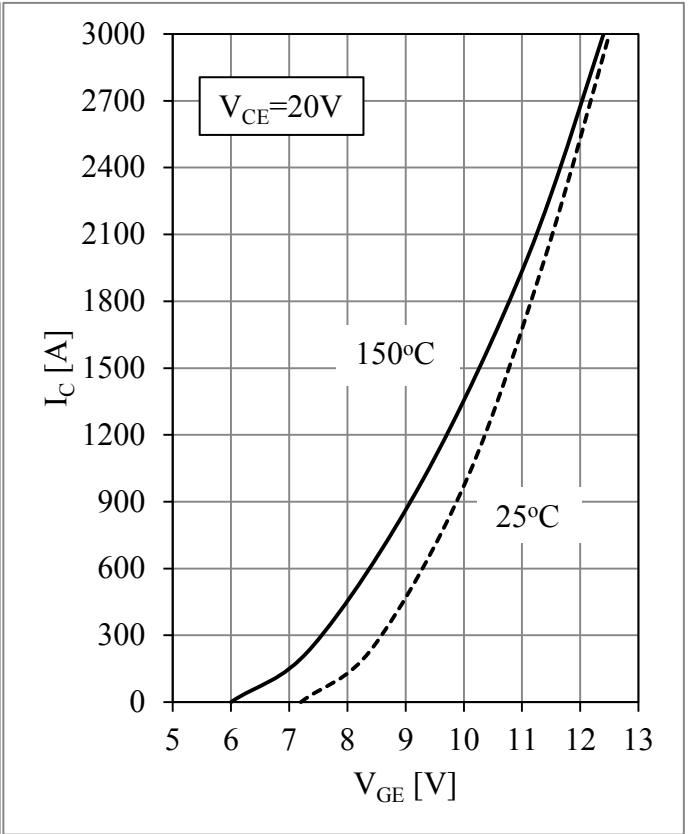


Fig 2. IGBT Transfer Characteristics

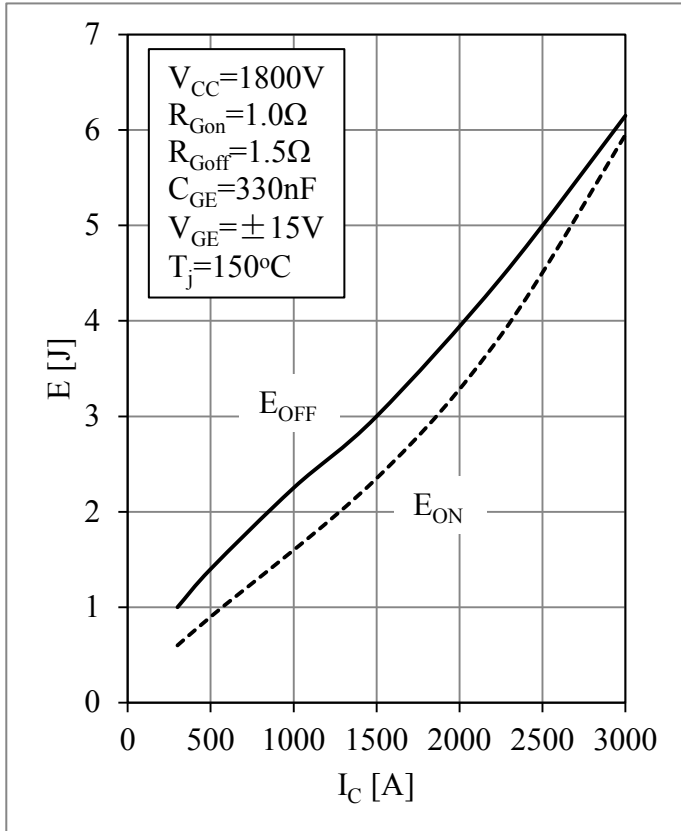


Fig 3. IGBT Switching Loss vs. I_C

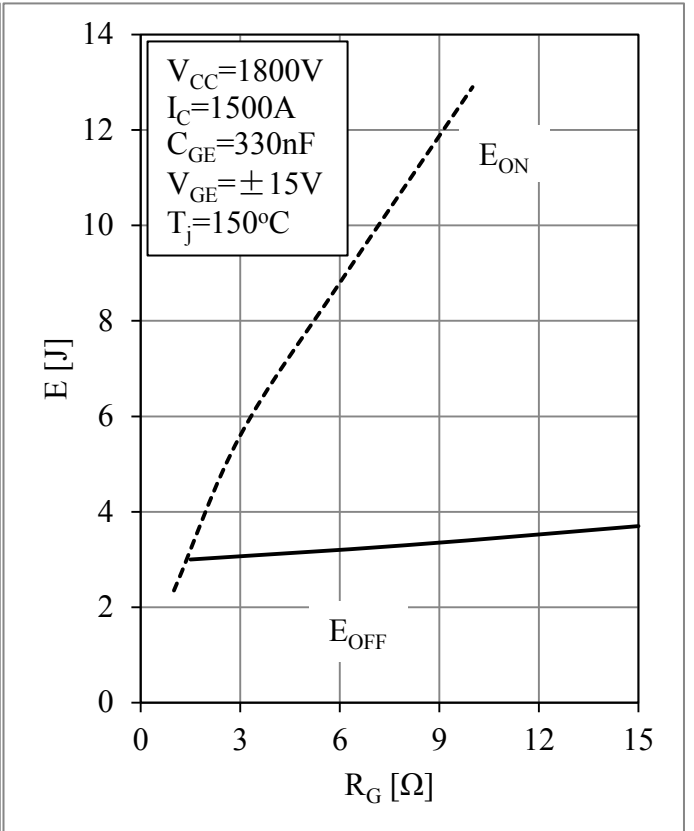


Fig 4. IGBT Switching Loss vs. R_G

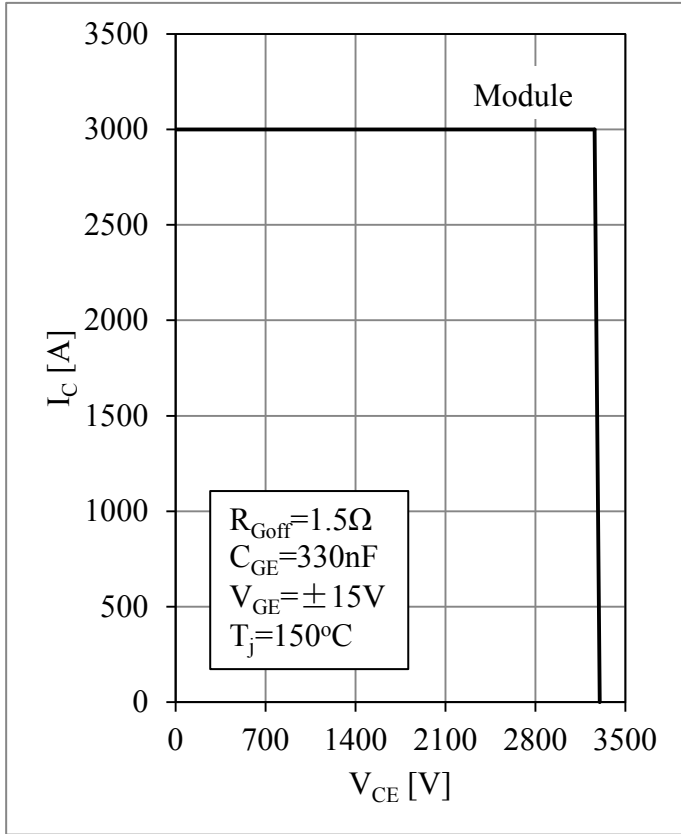


Fig 5. RBSOA

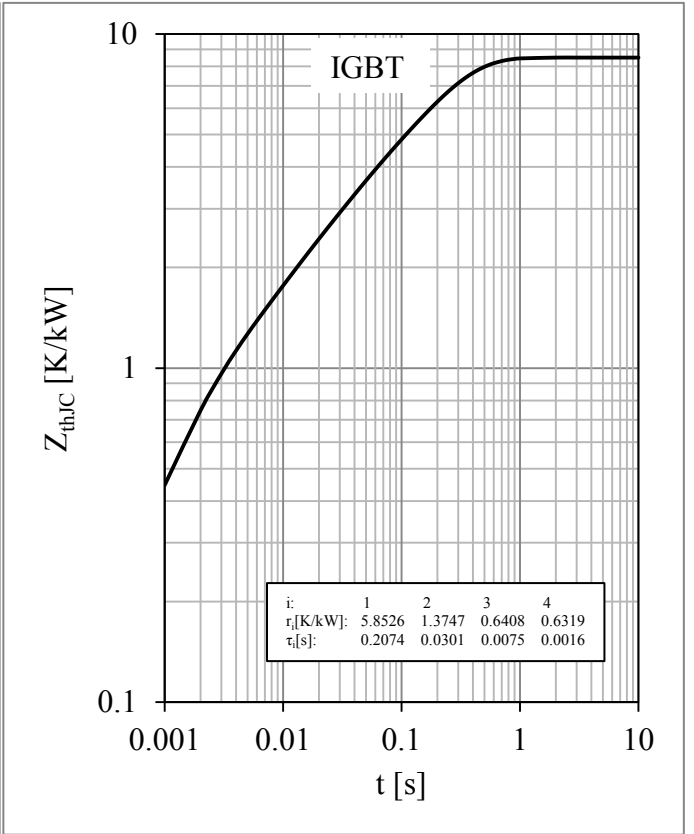


Fig 6. IGBT Transient Thermal Impedance

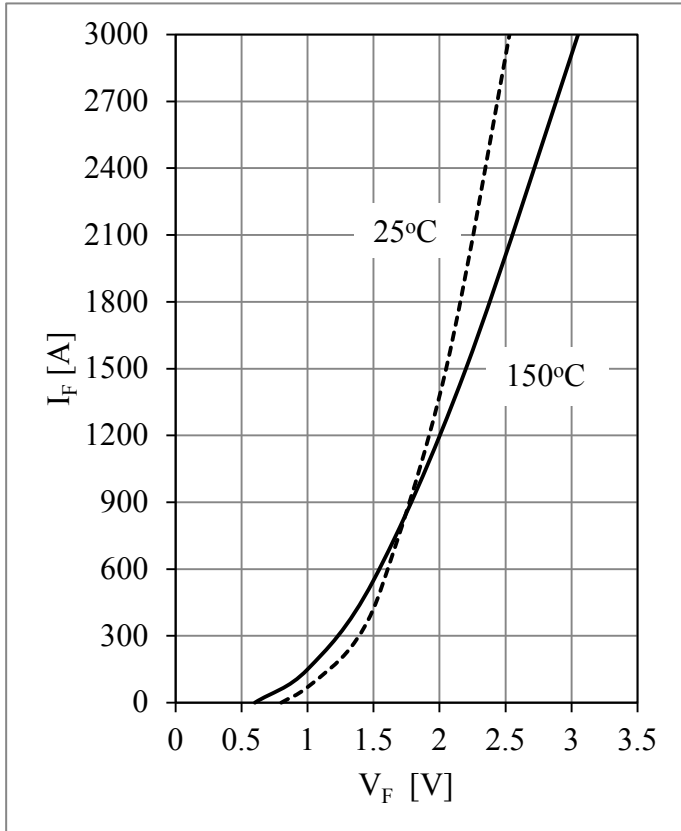


Fig 7. Diode Forward Characteristics

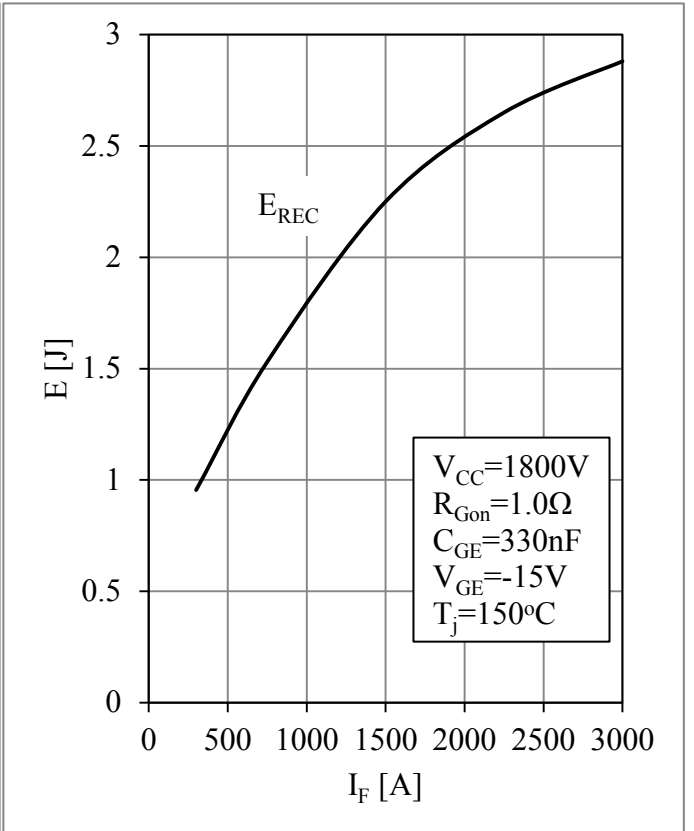


Fig 8. Diode Switching Loss vs. I_F

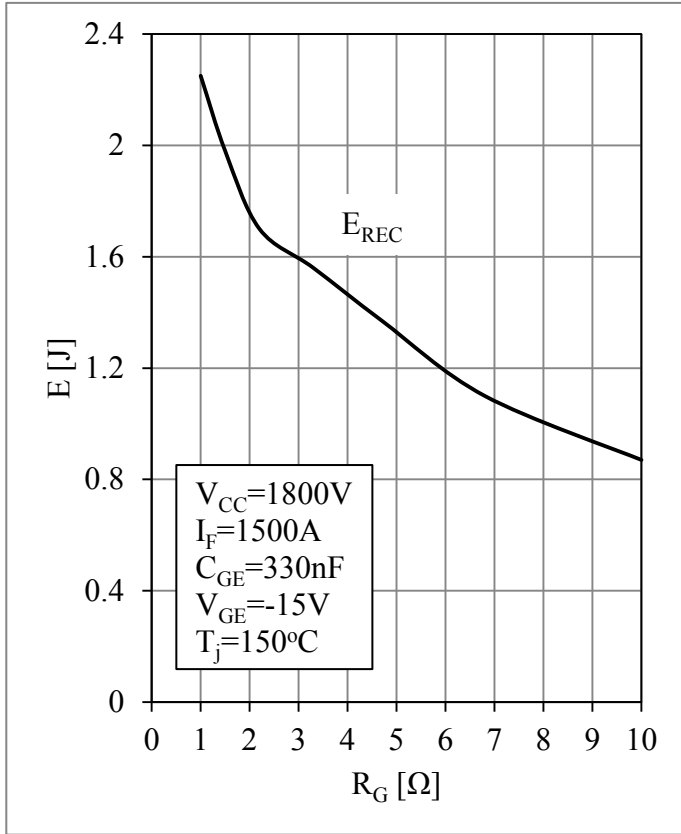


Fig 9. Diode Switching Loss vs. R_G

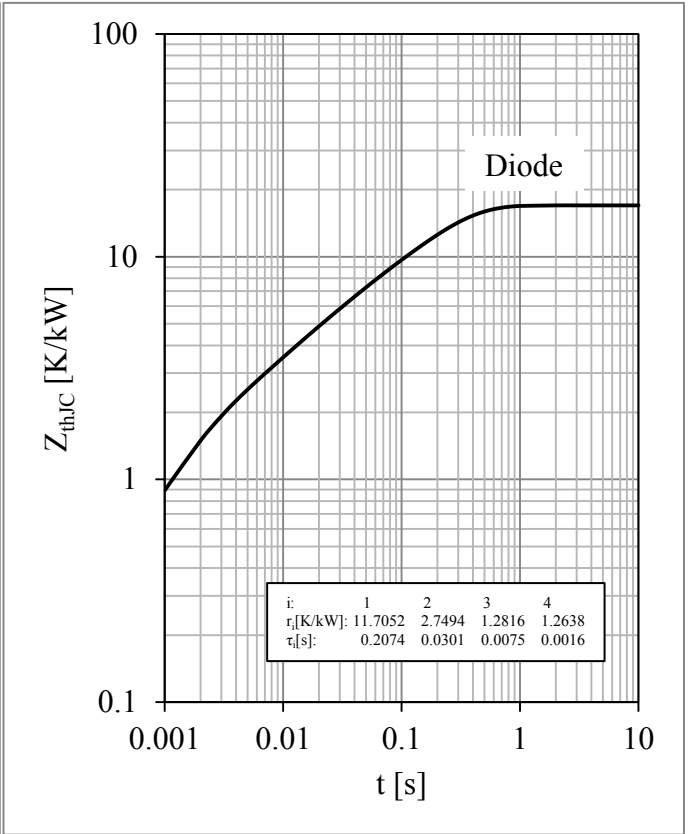
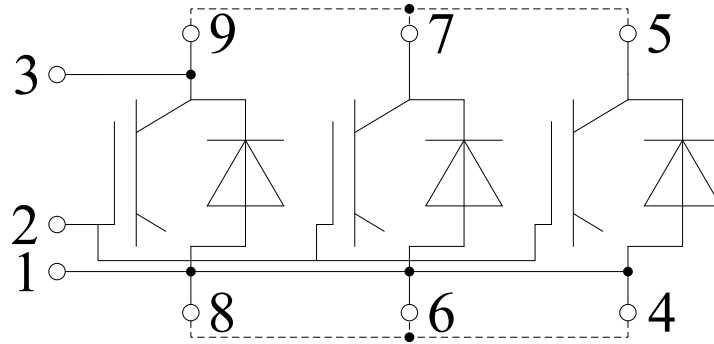


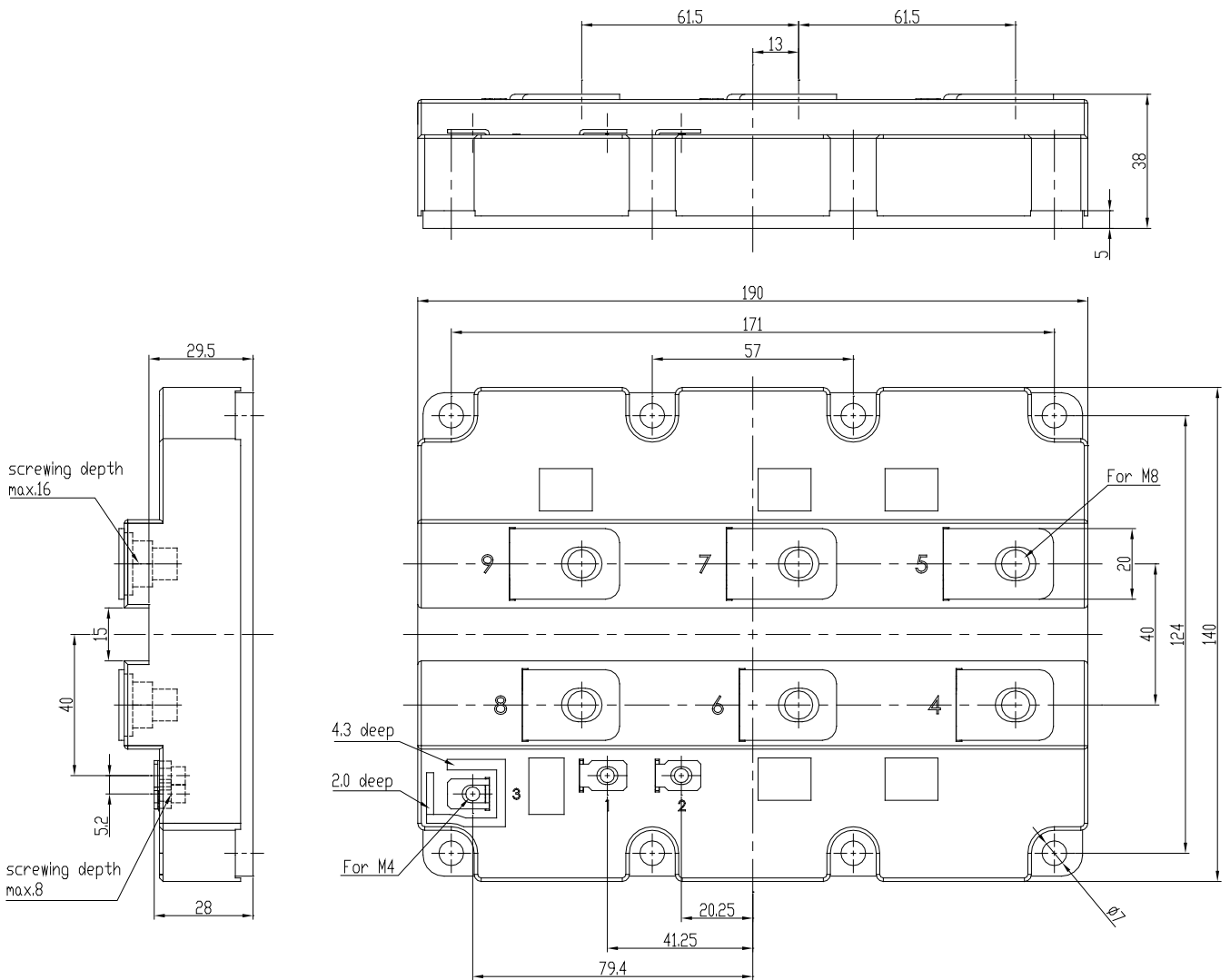
Fig 10. Diode Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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